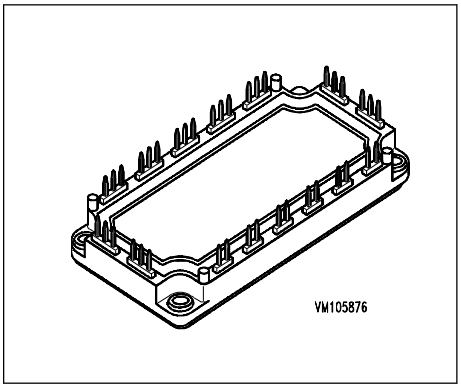
IGBT Power Module



- Solderable Power module
- 3-phase full-bridge
- Including fast free-wheel diodes
- Package with insulated metal base plate

Type	V_{CE}	I_C	Package	Ordering Code
BSM 75 GD 120 DN2	1200V	103A	ECONOPACK 3	C67070-A2516-A67

Maximum Ratings

Parameter	Symbol	Values	Unit
Collector-emitter voltage	V_{CE}	1200	V
Collector-gate voltage R_{GE} = 20 kΩ	V_{CGR}	1200	
Gate-emitter voltage	V_{GE}	± 20	
DC collector current T_C = 25 °C T_C = 80 °C	I_C	103 75	A
Pulsed collector current, t_p = 1 ms T_C = 25 °C T_C = 80 °C	I_{Cpuls}	206 150	
Power dissipation per IGBT T_C = 25 °C	P_{tot}	520	W
Chip temperature	T_j	+ 150	°C
Storage temperature	T_{stg}	-40 ... + 125	
Thermal resistance, chip case	R_{thJC}	≤ 0.235	K/W
Diode thermal resistance, chip case	R_{thJCD}	≤ 0.55	
Insulation test voltage, t = 1min.	V_{is}	2500	Vac
Creepage distance	-	16	mm
Clearance	-	11	
DIN humidity category, DIN 40 040	-	F	sec
IEC climatic category, DIN IEC 68-1	-	40 / 125 / 56	

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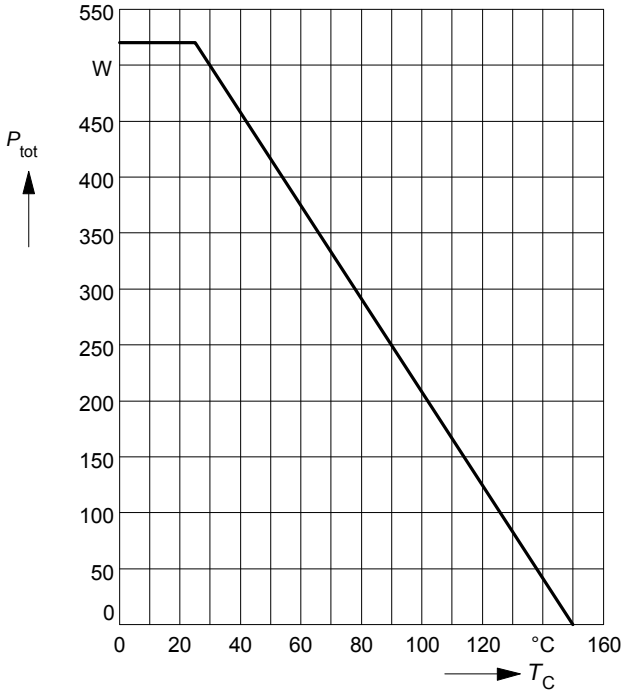
Electrical Characteristics, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Gate threshold voltage $V_{GE} = V_{CE}$, I_C = 3 mA	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter saturation voltage V_{GE} = 15 V, I_C = 75 A, T_j = 25 °C V_{GE} = 15 V, I_C = 75 A, T_j = 125 °C	$V_{CE(sat)}$	- -	2.5 3.1	3 3.7	
Zero gate voltage collector current V_{CE} = 1200 V, V_{GE} = 0 V, T_j = 25 °C V_{CE} = 1200 V, V_{GE} = 0 V, T_j = 125 °C	I_{CES}	- -	1 4	1.5 -	mA
Gate-emitter leakage current V_{GE} = 20 V, V_{CE} = 0 V	I_{GES}	-	-	320	nA
AC Characteristics					
Transconductance V_{CE} = 20 V, I_C = 75 A	g_{fs}	31	-	-	S
Input capacitance V_{CE} = 25 V, V_{GE} = 0 V, f = 1 MHz	C_{iss}	-	5.1	-	nF
Output capacitance V_{CE} = 25 V, V_{GE} = 0 V, f = 1 MHz	C_{oss}	-	0.72	-	
Reverse transfer capacitance V_{CE} = 25 V, V_{GE} = 0 V, f = 1 MHz	C_{rss}	-	0.38	-	

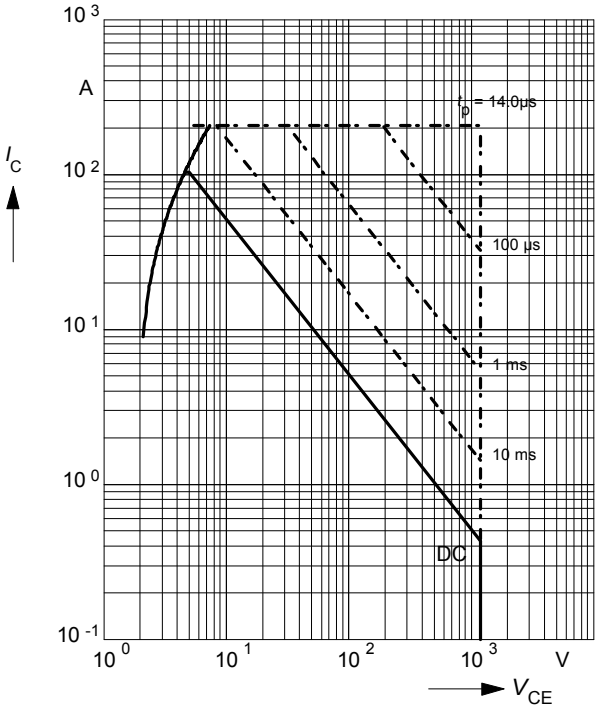
Electrical Characteristics, at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Switching Characteristics, Inductive Load at T_j = 125 °C					
Turn-on delay time V_{CC} = 600 V, V_{GE} = 15 V, I_C = 75 A R_{Gon} = 15 Ω	$t_{d(on)}$	- -	30 -	60 -	ns
Rise time V_{CC} = 600 V, V_{GE} = 15 V, I_C = 75 A R_{Gon} = 15 Ω	t_r	- -	70 -	140 -	
Turn-off delay time V_{CC} = 600 V, V_{GE} = -15 V, I_C = 75 A R_{Goff} = 15 Ω	$t_{d(off)}$	- -	450 -	600 -	
Fall time V_{CC} = 600 V, V_{GE} = -15 V, I_C = 75 A R_{Goff} = 15 Ω	t_f	- -	70 -	100 -	
Free-Wheel Diode					
Diode forward voltage I_F = 75 A, V_{GE} = 0 V, T_j = 25 °C I_F = 75 A, V_{GE} = 0 V, T_j = 125 °C	V_F	- -	2.3 1.8	2.8 -	V
Reverse recovery time I_F = 75 A, V_R = -600 V, V_{GE} = 0 V di_F/dt = -900 A/µs, T_j = 125 °C	t_{rr}	-	0.125	-	µs
Reverse recovery charge I_F = 75 A, V_R = -600 V, V_{GE} = 0 V di_F/dt = -800 A/µs, T_j = 25 °C di_F/dt = -800 A/µs, T_j = 125 °C di_F/dt = -900 A/µs, T_j = 25 °C	Q_{rr}	- -	3.2 10	- -	µC

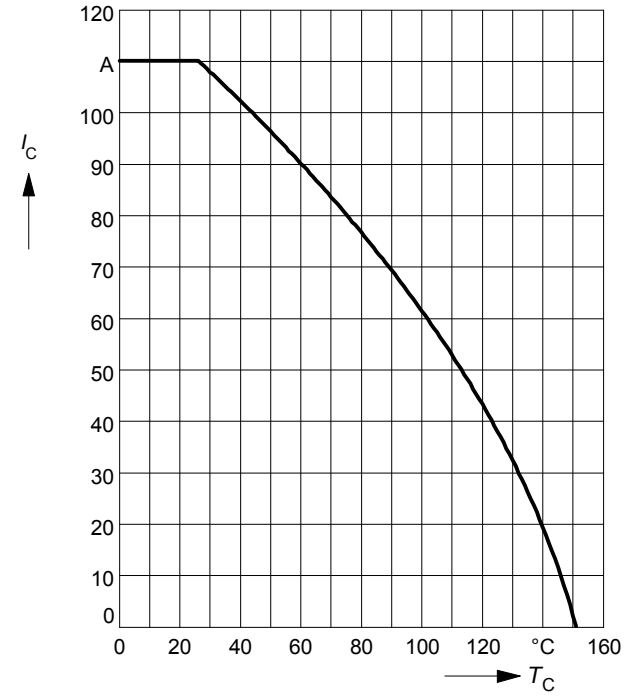
Power dissipation
$P_{tot} = f(T_C)$
parameter: $T_j \leq 150$ °C



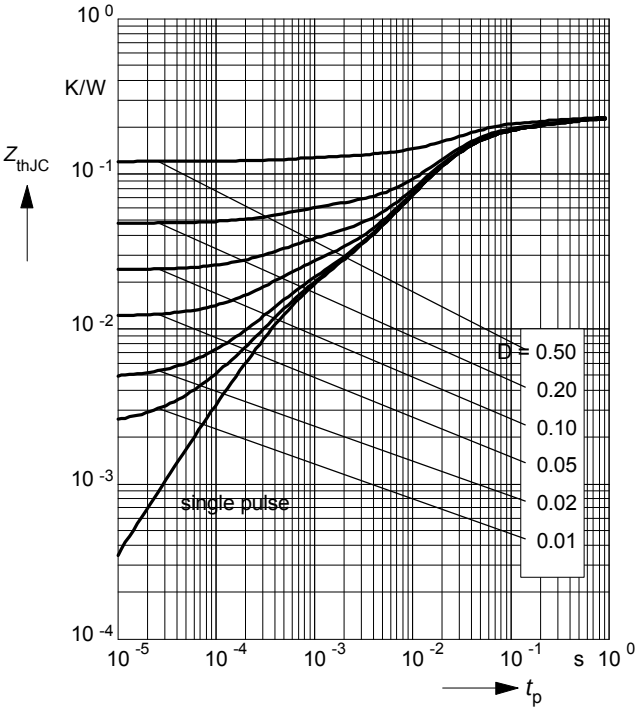
Safe operating area
$I_C = f(V_{CE})$
parameter: $D = 0$, $T_C = 25$°C , $T_j \leq 150$ °C



Collector current
$I_C = f(T_C)$
parameter: $V_{GE} \geq 15$ V , $T_j \leq 150$ °C



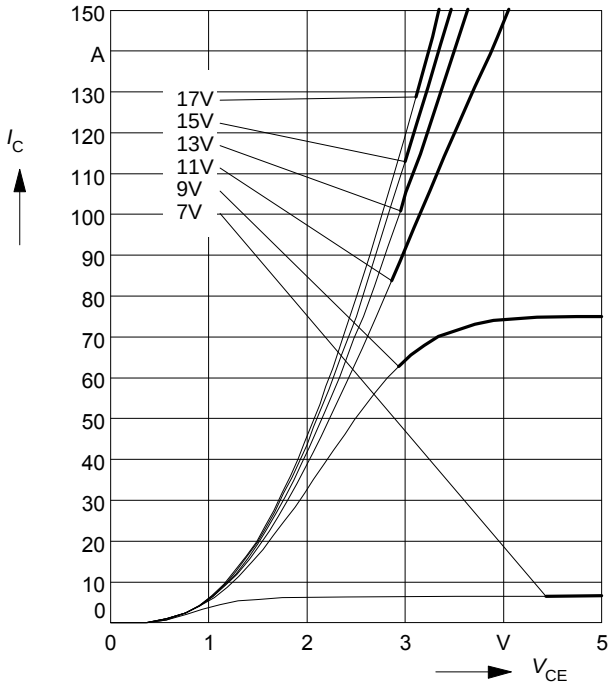
Transient thermal impedance IGBT
$Z_{th\,JC} = f(t_p)$
parameter: $D = t_p / T$



Typ. output characteristics

$I_C = f(V_{CE})$

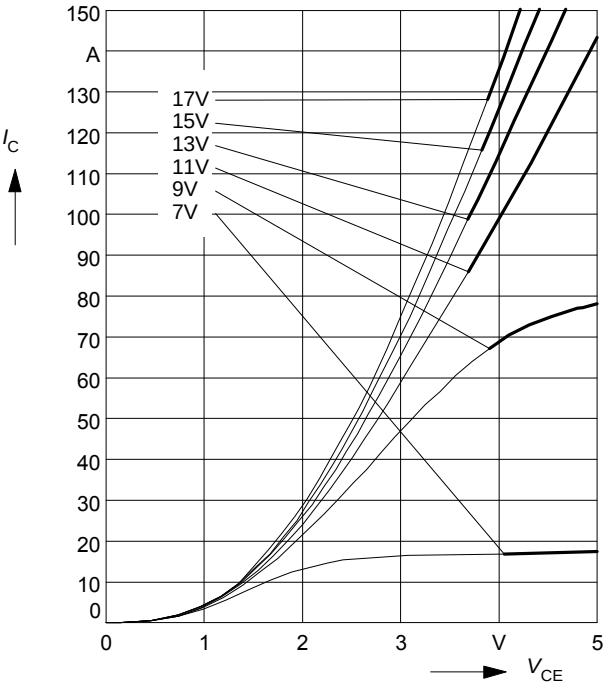
parameter: t_p = 80 µs, T_j = 25 °C



Typ. output characteristics

$I_C = f(V_{CE})$

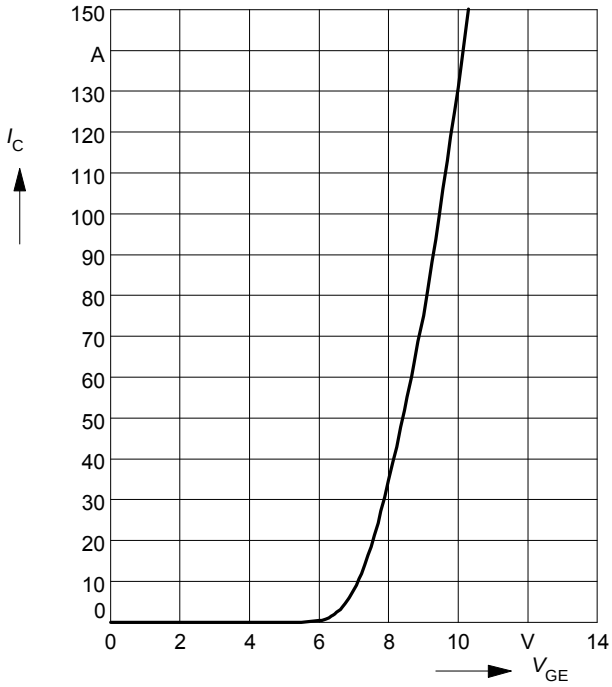
parameter: t_p = 80 µs, T_j = 125 °C



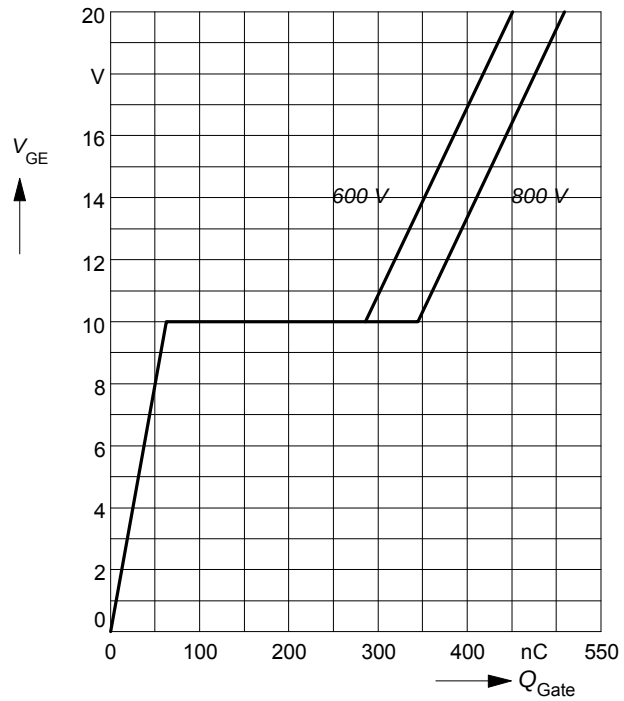
Typ. transfer characteristics

$I_C = f(V_{GE})$

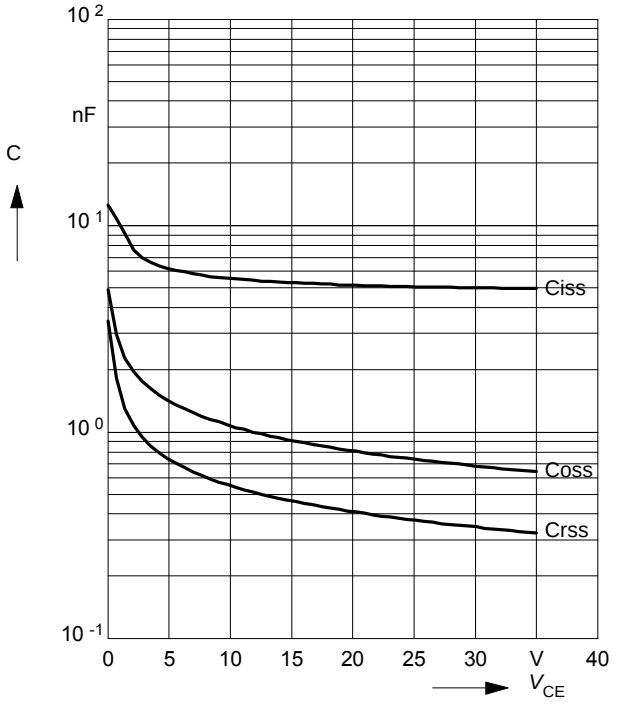
parameter: t_p = 80 µs, V_{CE} = 20 V



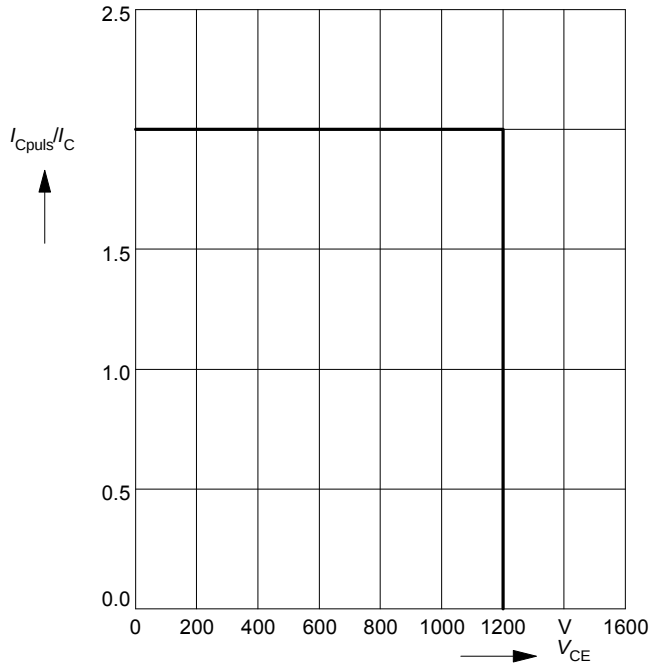
Typ. gate charge
$V_{GE} = f(Q_{Gate})$
parameter: $I_{C\ puls}$ = 75 A



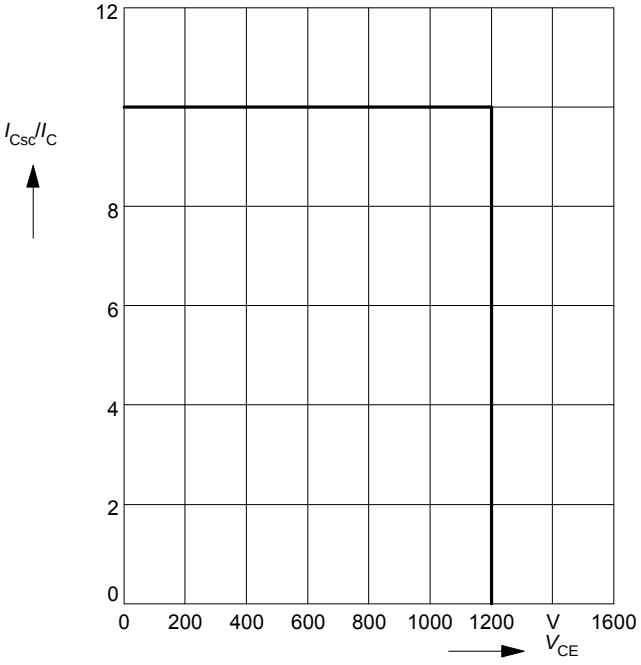
Typ. capacitances
$C = f\ (V_{CE})$
parameter: V_{GE} = 0 V, f = 1 MHz



Reverse biased safe operating area
$I_{Cpuls} = f(V_{CE})$, T_j = 150°C
parameter: V_{GE} = 15 V



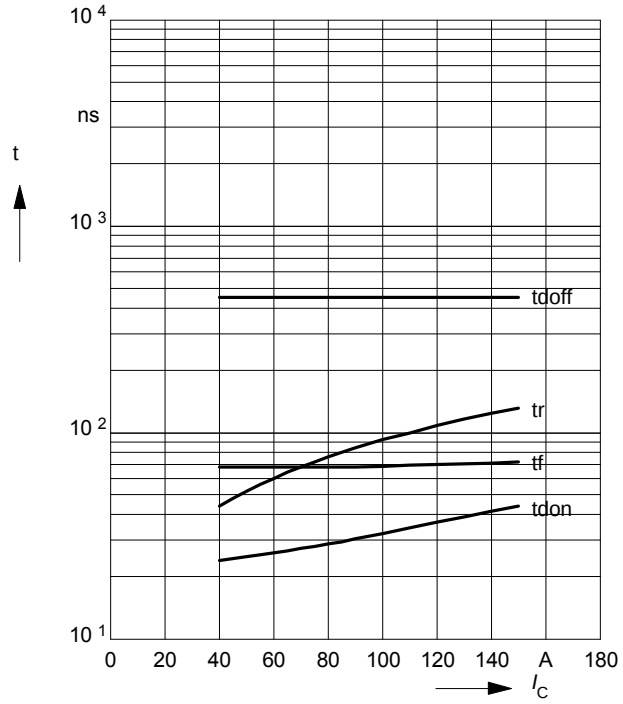
Short circuit safe operating area
$I_{Csc} = f(V_{CE})$, T_j = 150°C
parameter: V_{GE} = ± 15 V, t_{SC} ≤ 10 µs, L < 50 nH



Typ. switching time

$I = f(I_C)$, inductive load , T_j = 125°C

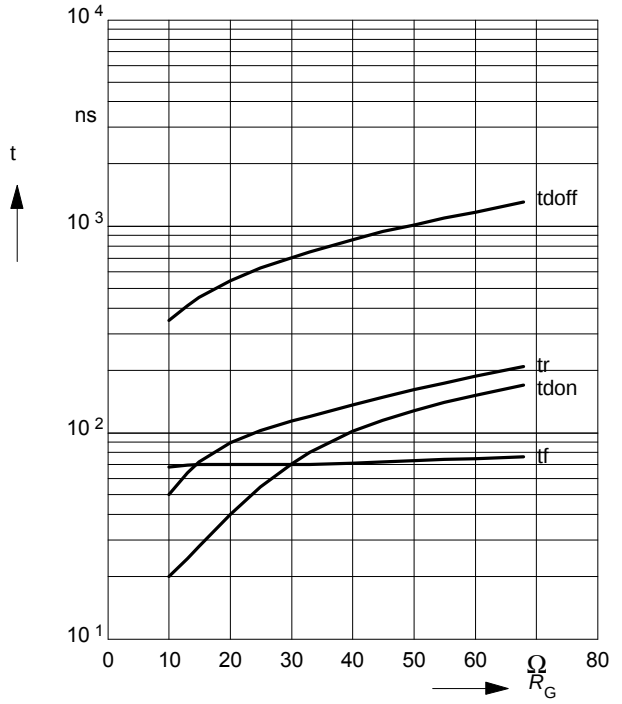
par.: V_{CE} = 600 V, V_{GE} = ± 15 V, R_G = 15 Ω



Typ. switching time

$t = f(R_G)$, inductive load , T_j = 125°C

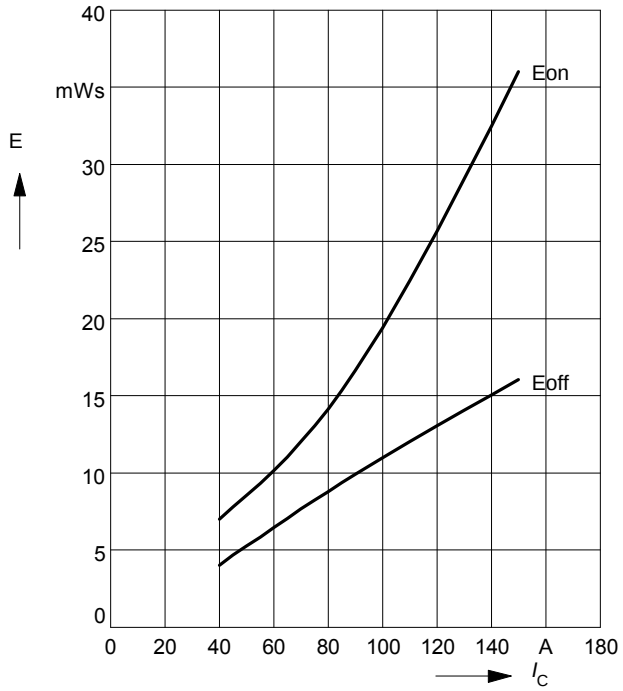
par.: V_{CE} = 600V, I_C = 75 A



Typ. switching losses

$E = f(I_C)$, inductive load , T_j = 125°C

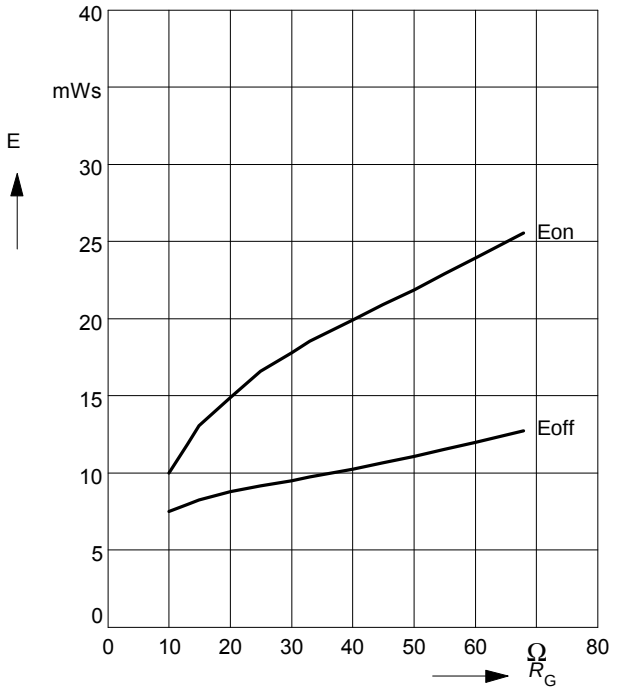
par.: V_{CE} = 600 V, V_{GE} = ± 15 V, R_G = 15 Ω



Typ. switching losses

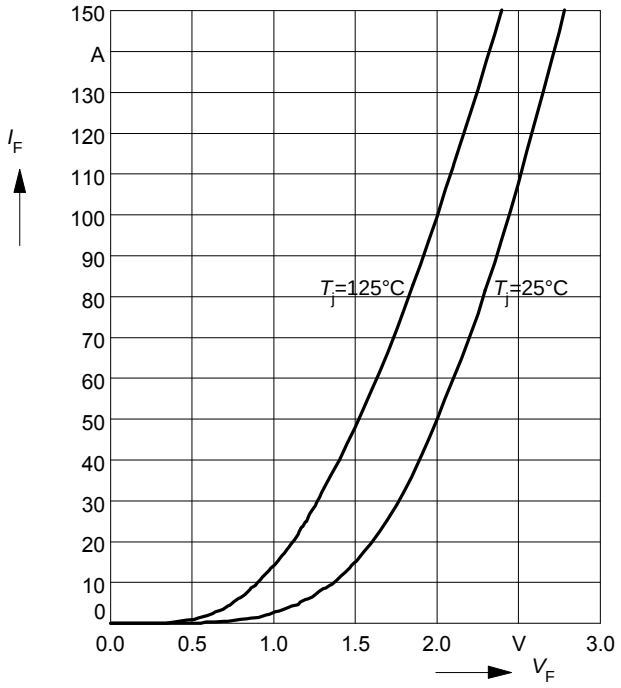
$E = f(R_G)$, inductive load , T_j = 125°C

par.: V_{CE} = 600V, V_{GE} = ± 15 V, I_C = 75 A



Forward characteristics of fast recovery reverse diode $I_F = f(V_F)$

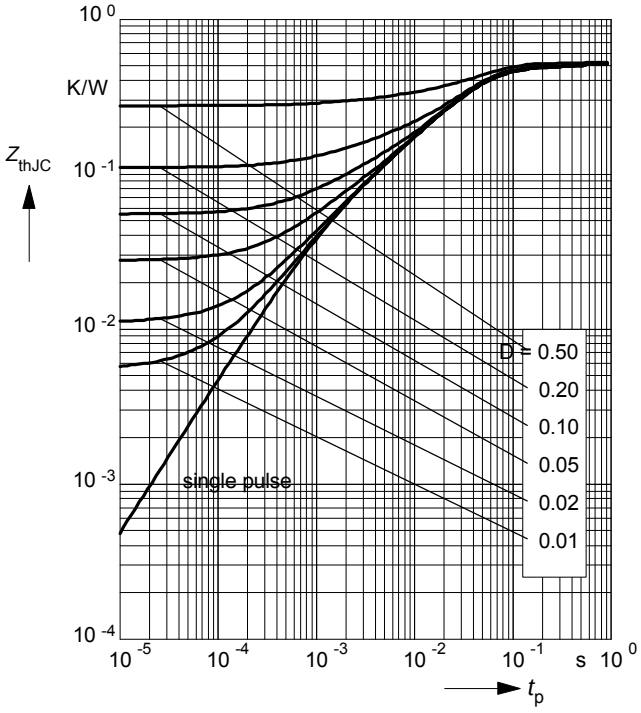
parameter: T_j



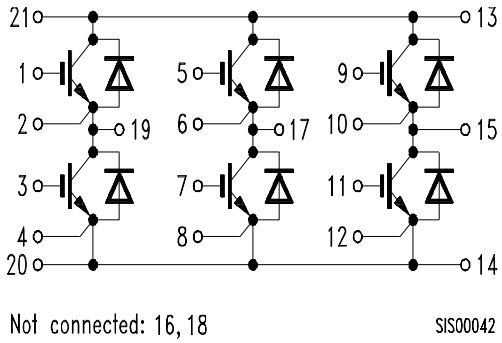
Transient thermal impedance Diode

$Z_{th\,JC} = f(t_p)$

parameter: $D = t_p / T$



Circuit Diagram



Package Outlines

Dimensions in mm

Weight: 300 g

